



No-clean flux paste for rework

PERFORMANCES

ECOFREC™ TF40 is a tacky flux paste designed for **rework and soldering** of traditional components, SMDs. ECOFREC™ TF40 is also very efficient for BGA repair.

SPECIFICATIONS

Colour	amber
Odour	very low
Solubility	not soluble
in water	
In alcohol	soluble
Classification according ANSI/J-STD-004	RELO RMA
Acid index (mg KOH /g)	87
Halogen %	0
Density at 20°C	1,03
Viscosity at 20°C Pa.s	500
<i>(Measured on BROOKFIELD RVT viscosimeter with Mobile F HELIPATH system, at 5 rpm).</i>	

CHARACTERISTICS

ECOFREC™ TF40 is a high viscosity paste made of a complex blending of resins, activators and solvents. After soldering, flux residues remaining on the PCB are non aggressive and not liable to corrosion. PCB cleaning is thus unnecessary.

PACKAGING TYPE

Syringe	10 g or 30 g
Plastic drum	200 g
Cartridge	300 g

STORAGE AND SHELF LIFE

Flux ECOFREC™ TF40 must be stored in a cool and ventilated area between 5° and 30°C. Shelf life is about one year long.



CONDITIONS OF USE

ECOFREC™ TF40 can be applied by dispensing or screen/stencil printing.

The sticky properties of Flux ECOFREC™ TF40 ensure that components are kept in position until the alloy is reflowed. A variety of heating methods may be used to produce the solderjoint with ECOFREC™ TF40 ; these include soldering irons, hot gas and hot bar devices, IR or convection oven or vapour phase.

Printing adhesive properties can be improved after 30-60 minutes storage or after heating at 50-60°C during few minutes.

HSE

During soldering operations, evolving vapours should be collected by an efficient exhaust system.

Please refer to MSDS before use.

This data is based on information that the manufacturer believe to be reliable and offered in good faith. In no event will AVANTEC be responsible for special, incidental and consequential damages. The user is responsible to the Administrative Authorities (regulations for the protection of the Environment) for the conformity of his installation.

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